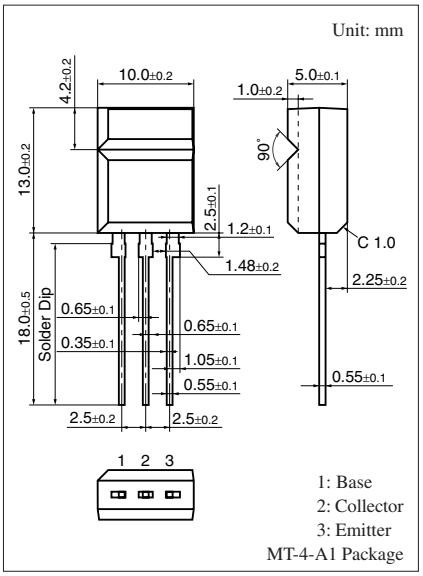
2SB1631

Silicon PNP epitaxial planar type

For power amplification



■ Features

- High forward current transfer ratio h_{FE} which has satisfactory linearity
- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Allowing automatic insertion with radial taping

■ Absolute Maximum Ratings $T_C = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	−60	V
Collector-emitter voltage (Base open)	V_{CEO}	−60	V
Emitter-base voltage (Collector open)	V_{EBO}	−6	V
Collector current	I_C	−3	A
Peak collector current	I_{CP}	−6	A
Base current	I_B	−1	A
Collector power dissipation	P_C	25	W
$T_a = 25°C$		2	
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 ~ +150	°C

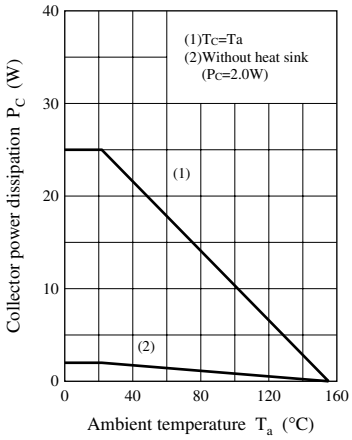
■ Electrical Characteristics $T_C = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -25$ mA, $I_B = 0$	−60			V
Collectot-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -60$ V, $I_E = 0$			−100	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -40$ V, $I_B = 0$			−100	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -6$ V, $I_C = 0$			−100	μA
Forward current transfer ratio	h_{FE} *	$V_{CE} = -4$ V, $I_C = -0.5$ A	300		700	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -2$ A, $I_B = -0.05$A			−1	V
Transition frequency	f_T	$V_{CE} = -12$ V, $I_C = -0.2$ A, f = 10 MHz		30		MHz

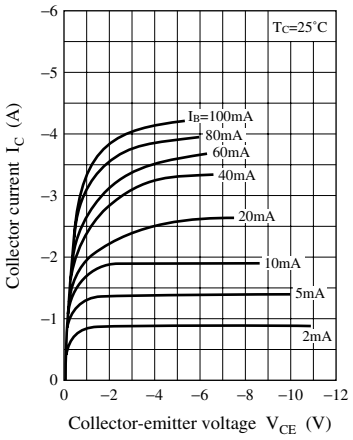
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *: Rank classification

Rank	Q	P
h_{FE}	300 to 500	400 to 700

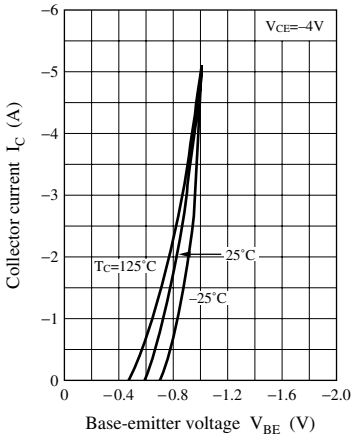
P_C — T_a



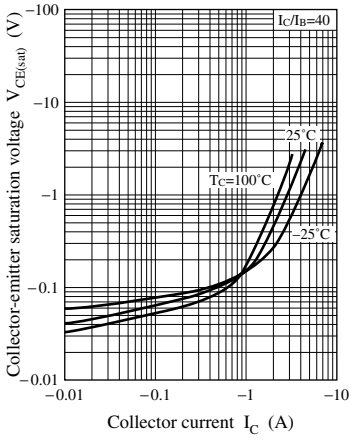
I_C — V_{CE}



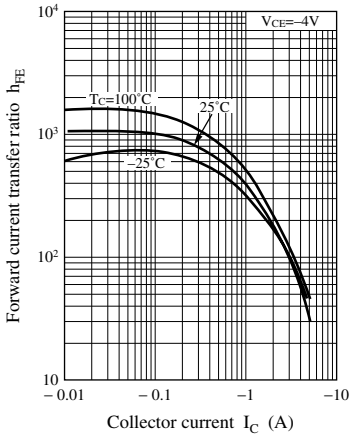
I_C — V_{BE}



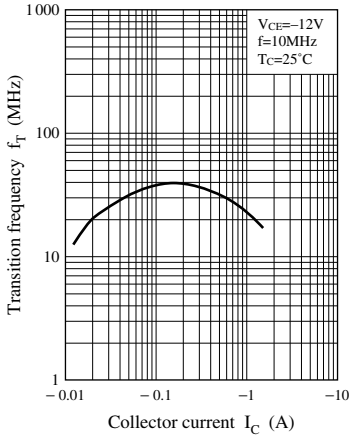
$V_{CE(sat)}$ — I_C



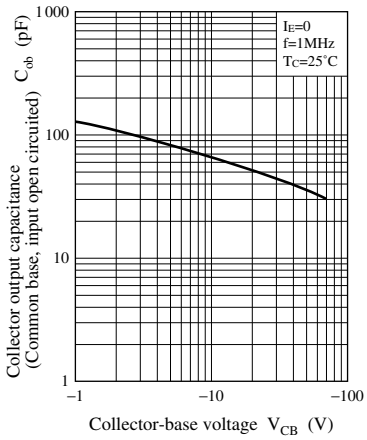
h_{FE} — I_C



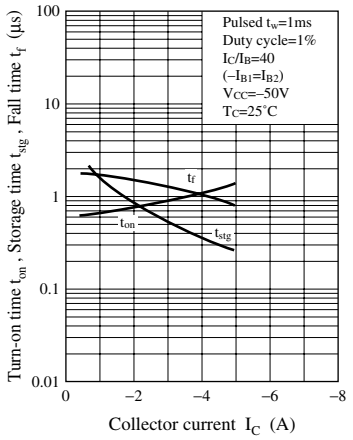
f_T — I_E



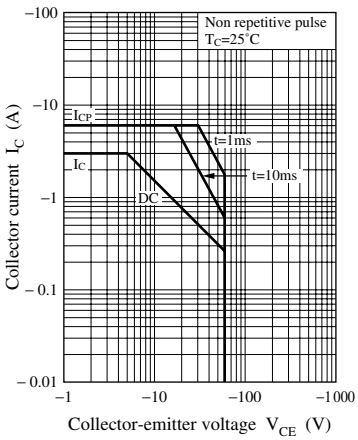
C_{ob} — V_{CB}



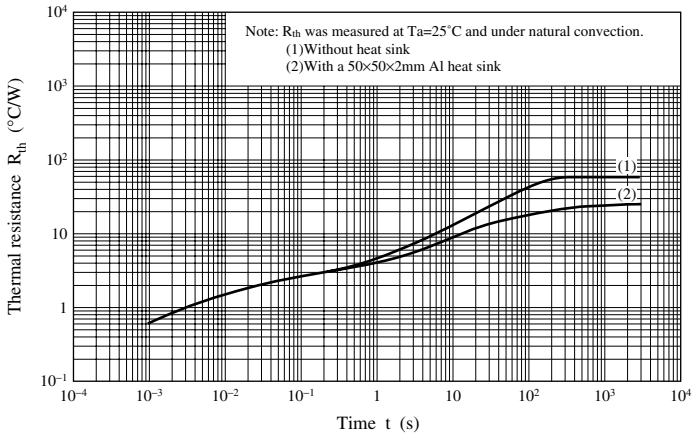
t_{on} , t_{stg} , t_f — I_C



Safe operation area



R_{th} — t


Note: Rth was measured at Ta=25°C and under natural convection.
(1)Without heat sink
(2)With a 50×50×2mm Al heat sink
(1)
(2)
Thermal resistance Rth (°C/W)
Time t (s)
10^4
10^3
10^2
10
1
10^–1
10^–4
10^–3
10^–2
10^–1
1
10
10^2
10^3
10^4

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